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Application Data Sheet 37 CFR 1				Attorney Docket Number				FIS9			
				Application Number							
Title of	f Invention	Method of For	ming Thin S	GOI Wafers	with High	h Rel	axation a	nd Low	/ Stacking Fa	ult Defect Density	
bibliogra This do	aphic data arrar cument may be	nged in a format sp	ecified by the onically and	United States submitted to the	Patent ar	nd Tra	demark O	ffice as	outlined in 37	ollowing form contair CFR 1.76. nic Filing System (E	
Secre	cy Orde	er 37 CFR	5.2								
										Secrecy Order po electronically.)	ursuant to
Appli	cant Info	ormation:									
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Applic	ant Author	ity <a>• Inventor	◯Legal F	Representativ	e under	35 l	J.S.C. 11	7	OParty of Ir	iterest under 35 U.	.S.C. 118
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Mailin	g Address	of Applicant:	•								
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Addre	ss 2										
City Wappingers Falls				State/Provi					nce NY		
Posta	Code	12590			Coun	tryi	US		•		
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Applic	ant Author	ity Inventor	◯Legal F	Representativ	e under	35 L	J.S.C. 11	7	OParty of Ir	iterest under 35 U.	S.C. 118
Prefix	Given Na	me		Middle Name					Family Name		
	Devendra		K.					Sadana			

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Application Data Sheet 37 CFR 1.7				Attorney Docket Number			FIS920030342US1					
Application Data Sheet 37 Cl K				Application Number								
Title of	Invention Me	thod of Forming Thin S	sgo	l Wafers with	ı Hiç	gh Re	laxation a	nd Low S	Stacking Fau	ılt Defect	Density	
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	g Address of Ap	* *										
Addres	<u> </u>	90 Sky Top Drive										
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City	Pleasantville	<u> </u>				Stat	e/Provin	nce NY				
Postal	Code	10570		Countryi US								
Applica	ant 4									Remov	ve	
	ant Authority ①	Inventor Cegal	Rep	resentative u	nde	r 35 l	U.S.C. 117	7)Party of Int	terest und	 der 35 U.:	S.C. 118
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Mailing	g Address of Ap	plicant:										
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City	LaGrangevil	le				Stat	e/Provin	ce	NY			
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		Number or complete see 37 CFR 1.33(the Corres	pon	dend	e Inform	ation s	ection bel	ow.		
Ar	n Address is bei	ing provided for th	e co	rresponde	nce	e Info	rmation	of this	applicatio	n.		
Custor	mer Number	32074										
Email /	Address								Add E	mail	Remov	e Email
Applic	cation Infor	mation:										
Title of	f the Invention	Method of Form	ing 7	Thin SGOI W	afer	rs with	High Rel	axation a	and Low Sta	cking Fa	ult Defect	Density
Attorne	ey Docket Numl	per FIS920030342U										
Applica	ation Type	Nonprovisional	 onprovisional									
Subjec	t Matter	Utility										
Sugge	sted Class (if ar	ıy)				s	ub Class	if any	·)			
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Application Data	She	et 37 CFR 1.76		Docket Number	FIS920030:	342US1		
			Application	on Number				
Title of Invention	Method	of Forming Thin SGO	I Wafers wit	th High Relaxation a	and Low Stack	ing Fault Defe	ect Density	
Publication Informa	ition:							
Request Early P	Publicat	tion (Fee required at	time of Re	equest 37 CFR 1.2	219)			
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Customer Number	3	32074						
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Prior Application S Application Numb		Pending	Type	Brian Applicat	ion Number		te (YYYY-MM-DD)	
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Additional Domestic the Add button.	Priority	y Data may be gen	erated with	nin this form by s	selecting	A	dd	
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This section allows for the applicant to claim benefit of foreign priority and to identify any prior foreign application for which priority is not claimed. Providing this information in the application data sheet constitutes the claim for priority as required by 35 U.S.C. 119(b) and 37 CFR 1.55(a).								
A 1' (' b) 1			·	D (E): 5			nove	
Application Numb	per	Country	/ '	Parent Filing D	vate (YYYY-N	אואי)	Priority Claimed • Yes No	
Additional Foreign Priority Data may be generated within this form by selecting the Add button. Add								
Assignee Infori	matio	on:						
Providing this information of the CFR to have an a	on in the	e application data she		substitute for compl	iance with any	requirement	of part 3 of Title 37	
Assignee 1						Rer	nove	
If the Assignee is an	Organi	ization check here.	√					

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Application Data Sheet 37 CFR 1.76			Attorney Docket Number	FIS920030342US1			
Application ba	ita One	30107 0110 1170	Application Number				
Title of Invention	Metho	d of Forming Thin SGC	I Wafers with High Relaxation a	nd Low Stacking Fault Defect Density			
Organization Name	€ In	iternational Business M	achines Corporation				
Mailing Address I	nforma	tion:					
Address 1 New Orchard Road							
Address 2							
City Armor		Armonk	State/Provi	nce NY			
Country i US			Postal Code	10504			
Phone Number			Fax Number				
Email Address							

Signature:

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Signature	/Yuanmin Cai /		Date (YYYY-MM-DD)	2006-07-10				
First Name	Yuanmin	Registration Number	56513					

Additional Assignee Data may be generated within this form by selecting the Add

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